

#### **Additive Manufacturing Research (APG)**



S&T Campaign: Materials Research

Manufacturing Science

Larry Holmes, (410) 306-4951 larry.r.holmes.civ@mail.mil

# Additive, Direct Write and Hybrid Manufacturing for a 3D ARMY

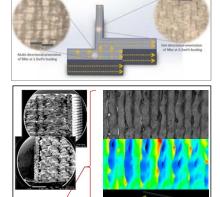


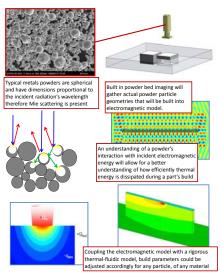
#### **Research Objective**

- Control material-process-property relationship for lightweightening and multifunctionality of critical warfighter components
- Process characterization to feed process modeling that will aid in the prediction of effects of AM
- Apply research to field-ready applications to reduce the Army's logistical burdens

#### **Unique ARL Facilities**

- Full and open access to ALL of the processing parameters for all of the DW and AM equipment in the MiCRO lab
- Feedstock pedigree is 100% verifiable for the AM compliable polymers, metals, and ceramics that are created in-house
- Laser sintering/melting of metals, polymers and ceramics in one platform
- Field-aided vat polymerization for tailored internal structure of 3D composites
- · Fiber reinforced thermoplastic micro-extrusion
- Multi-material vat polymerization
- Capillary Cold Spray
- FDM, SL, DLP-SL, SLS, DMLS, LOM



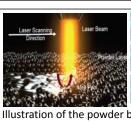






- Line Scanning of 3D objects
- Thermoplastic Extrusion (up to 400°) of filament, powder or pellet feedstock
- Thermoset Deposition
- •Ink Deposition
- 6-Axis Motion Control
- Tool Switching
- •Pick-n-Place
- •Micro-milling
- Laser Sintering
- •Aerosol Deposition
- Micro Cold Spray Deposition





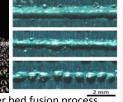
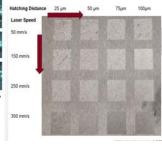


Illustration of the powder bed fusion process (i.e. DMLS), with single trace bead formation through variance in processing parameters and shear punch characterization specimen matrix



## **Challenges**

- Many current COTS materials are not applicable to future Army systems
- In-situ characterization is complicated by processing energies and environments required in these manufacturing systems
- Process modeling and simulation is slow to catch up to processing technologies

### **Complementary Expertise Sought**

- In-situ characterization of matter-energy interaction
- Process modeling for geometric, topological and on-the-fly optimization
- Field-aided processing: electric field, magnetic field, acoustic field, etc.
- Materials and process development: conductive (5+ μΩ/sq), dielectric (50+ κ), exotic, etc.
- Design/development of conformal and awkward passive devices